

[DESCRIPTION OF A MARK]

101     A substrate  
102a, 102b and 102c     First wiring lines  
103     A first insulating layer  
104 and 105     Active layers  
106     A second insulating layer  
107a, 107b, 107c and 107d     Second wiring lines  
(107a1, 107b1, 107c1 and 107d1     First conductive layers  
107a2, 107b2, 107c2 and 107d2     Second conductive layers  
107d3     A third conductive layer)  
108     A first interlayer insulating layer  
109~111     Third wiring lines  
(109, 110     Source wiring lines  
111     A drain wiring line)

201     A substrate  
202a, 202b and 202c     First wiring lines  
203     A first insulating layer  
204     An active layer  
205     A second insulating layer  
206a, 206b and 206c     Second wiring lines  
(206a1, 206b1 and 206c1     First conductive layers  
206a2, 206b2 and 206c2     Second conductive layers  
206a3     A second conductive layer)  
207     A capacitor wiring line  
(207a     A first conductive layer  
207b     A second conductive layer)  
208     A first interlayer insulating layer  
209     A source wiring line  
210     A drain wiring line  
211     A second interlayer insulating layer  
212     Black masks  
213     A third interlayer insulating layer  
214     A pixel electrode  
215 and 216     Channel formation regions

601 A substrate with an insulating surface  
602 A pixel matrix circuit  
603 A source driver circuit  
604 A gate driver circuit  
605 A signal processing circuit  
606 An FPC  
1007 An opposite substrate

701 A pixel matrix circuit  
702a and 703a Shift register circuits  
702b and 703b Level shifter circuits  
702c and 703c Buffer circuits  
703d A sampling circuit  
704 A precharge circuit

2001 A main body  
2002 An audio output unit  
2003 An audio input unit  
2004 A display device  
2005 Operation switches  
2006 An antenna

2101 A main body  
2102 A display device  
2103 An audio input unit  
2104 Operation switches  
2105 A battery  
2106 An image receiving unit

2201 A main body  
2202 A camera unit  
2203 An image receiving unit  
2204 Operation switches  
2205 A display device

2301 A main body

2302	Display devices
2303	Arm units
2401	A main body
2402	A light source
2403	A display device
2404	A polarization beam splitter
2405	Reflector
2406	Reflector
2407	A screen
2501	A main body
2502	A light source
2503	A display device
2504	An optical system
2505	A screen

[BRIEF DESCRIPTION OF THE FIGURES]

[Fig. 2](A)	画素TFT部 --- A pixel TFT portion
	保持容量部 --- A storage capacitor portion
(B)	保持容量部 --- A storage capacitor portion
[Fig. 3](A)	リンの添加工程 --- A phosphorus doping step
(B)	ボロンの添加工程 --- A boron doping step
(C)	裏面露光工程、リンの添加工程 --- A back side exposure step, A phosphorus doping step
[Fig. 9](A)	画素TFT部 --- A pixel TFT portion
	保持容量部 --- A storage capacitor portion
(B)	画素TFT部 --- A pixel TFT portion
	保持容量部 --- A storage capacitor portion
[Fig. 10](B)	画素TFT部 --- A pixel TFT portion
	保持容量部 --- A storage capacitor portion
[Fig. 11](B)	画素TFT部 --- A pixel TFT portion

- 保持容量部 --- A storage capacitor portion
- [Fig. 12](A) リンによるゲッタリング工程 --- A gettering step  
by phosphorus
- (C) ボロンの添加工程 --- A boron doping step
- (D) 裏面露光工程、リンの添加工程 --- A back side  
exposure step, A phosphorus doping step